

SH3838F85CQ00 Datasheet

Infrared Emitter

3838 Series (850nm) - 80°



Applications

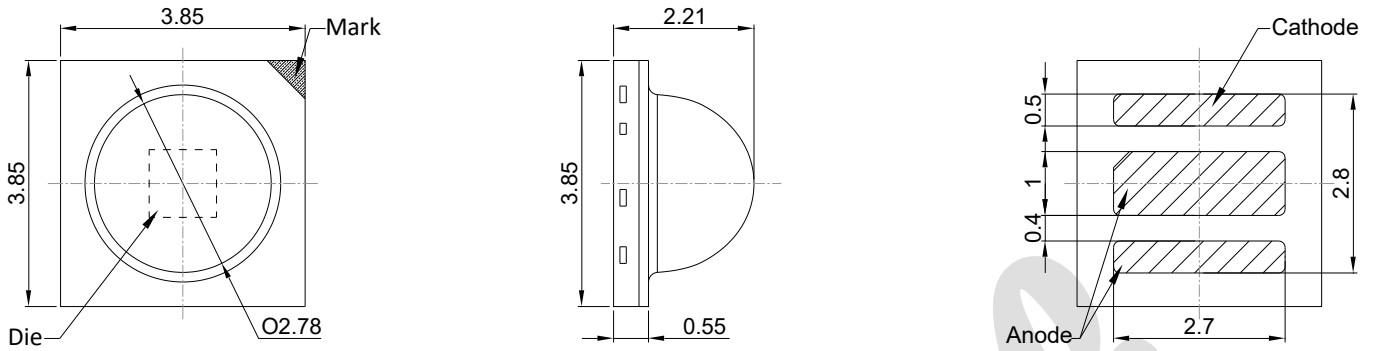
- Security System
- Automotive

Features

- Package: clear silicone
- Corrosion robustness class: 3B
- ESD: 2KV (HBM : MIL STD 883 Class 2)
- IR light source with high efficiency
- Single junction emitter
- Qualifications: AEC-Q102 Qualified
- Low thermal resistance (Max. 9 K/W)
- Peak wavelength 850 nm
- Optimized for high current pulse operation
- RoHS 2.0 and REACH compliant
- MSL 2 qualified according to J-STD 020

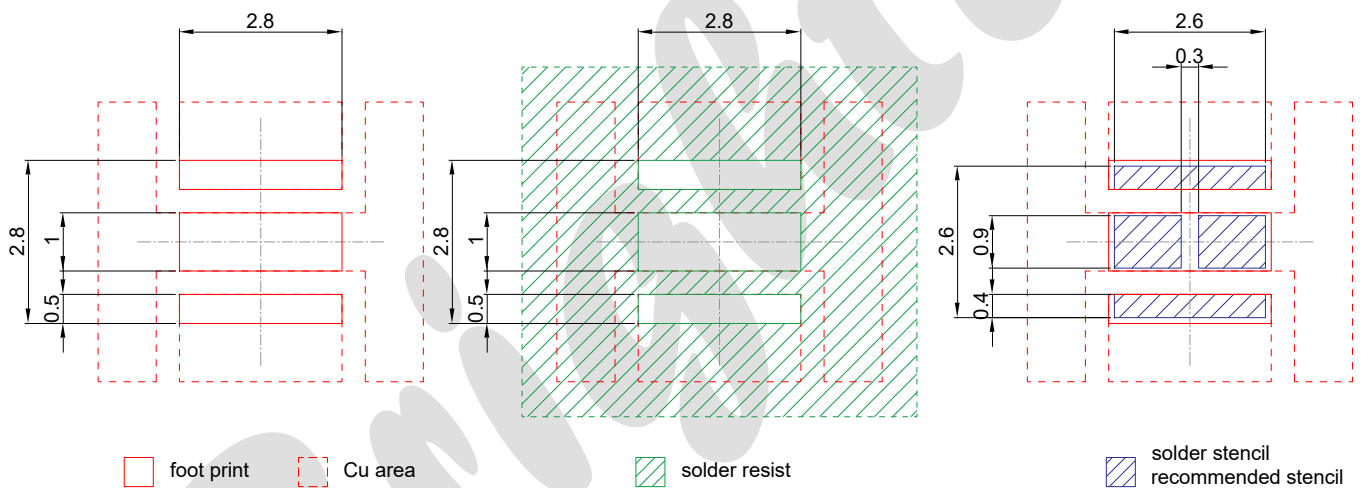
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Dimensional Drawing



1. Dimensions are in millimeters.
2. General tolerance is $\pm 0.05\text{mm}$.

Recommended Solder Pad



Component Location on Pad

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Maximum Ratings

T_A : 25 °C

Parameter	Symbol	Rating
Forward current	I_F	max. 1000 mA
Power consumption	P_{tot}	max. 2 W
Pulse forward current	I_{PF}	max. 3 A
Reverse voltage	V_R	max. 5 V
Junction temperature	T_j	max. 115 °C
Operating temperature	T_{op}	min. -40 °C
		max. 105 °C
Storage temperature	T_{stg}	min. -40 °C
		max. 105 °C
Soldering temperature	T_{sol}	max. 260 °C
Thermal resistance junction	R_{th}	typ. 4.5 K/W
		max. 9 K/W
ESD withstand voltage (HBM : MIL STD 883 Class 2)	V_{ESD}	max. 2 kV

1. For other ambient, limited setting of current will depend on de-rating curves.
2. When drive on maximum current, Junction temperature must be kept below 115°C.

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Characteristics

I_F : 1A | t_p : 10 ms | T_A : 25°C

Parameter	Symbol	Values
Peak wavelength	λ_p	typ. 850 nm
Spectral bandwidth	$\Delta\lambda$	typ. 35 nm
View angle	$2\theta_{1/2}$	typ. 80 °
Total radiant power $I_F = 1\text{ A}; t_p = 100\mu\text{s}$	Φ_e	min. 800 mW typ. 950 mW max. 1100 mW
Radiant intensity $I_F = 1\text{ A}; t_p = 100\mu\text{s}$	I_E	min. 400 mW/sr typ. 500 mW/sr max. 600 mW/sr
Forward voltage $I_F = 1\text{ A}; t_p = 100\mu\text{s}$	V_F	min. 1.5 V typ. 1.7 V max. 2.0 V
Reverse current ($V_R=5\text{V}$)	I_R	max. 10 μA

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Brightness Groups

Total radiant power $I_F : 1A$ | $t_p : 10$ ms

Group	min. Φ_e	max. Φ_e
PA8	800 mW	900 mW
PA9	900 mW	1000 mW
PB0	1000 mW	1100 mW

Forward voltage $I_F : 1A$ | $t_p : 10$ ms

Group	min. V_F	max. V_F
DF	1.5 V	2.0 V

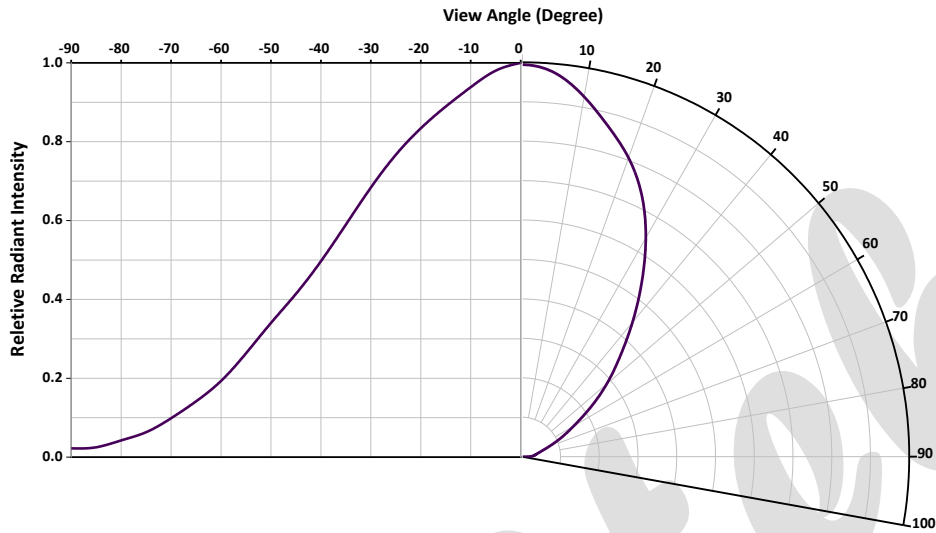
Peak wavelength $I_F : 1A$ | $t_p : 10$ ms

Group	min. λ_p	max. λ_p
F3	840 nm	870 nm

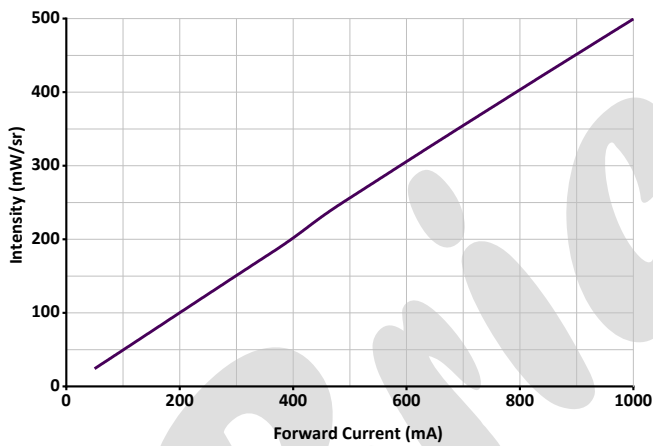
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Typical Electrical Optical Characteristics Curves

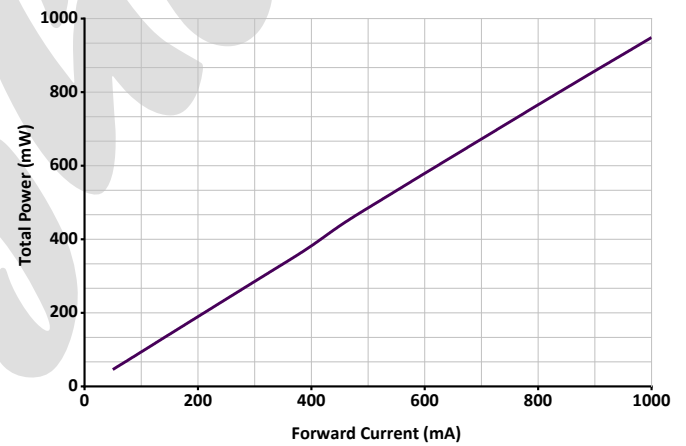
Radiation Characteristics(L=0)



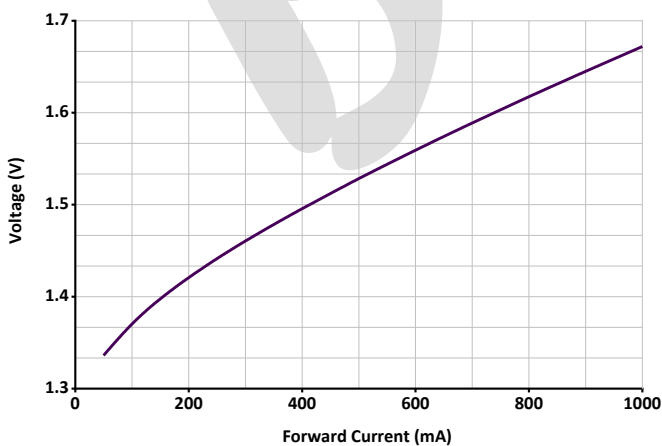
Radiant Intensity



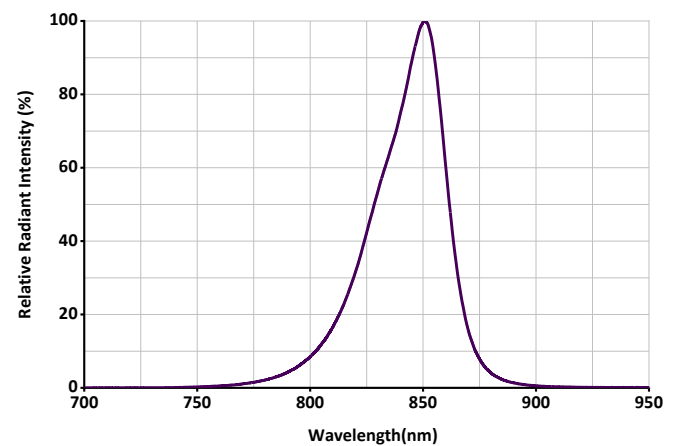
Total Radiant Power



Forward Voltage



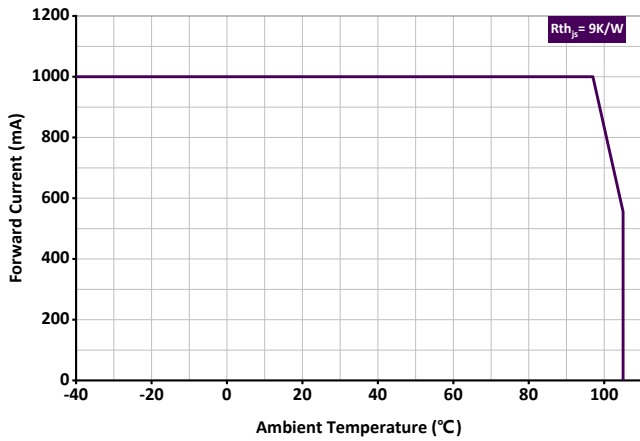
Relative Spectral Emission



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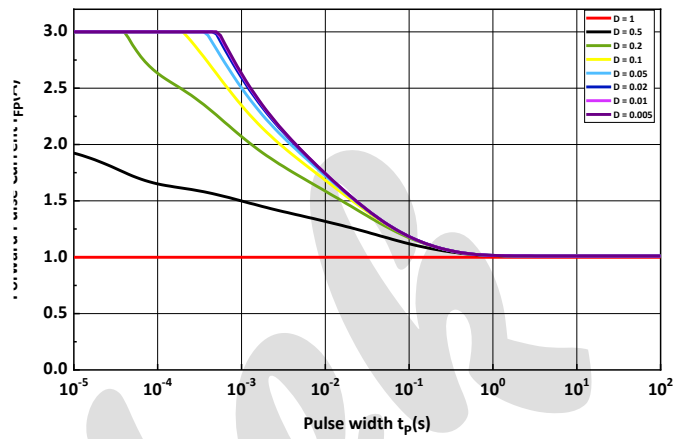
Permissible Forward Current

$$I_{F,max} = f(T_S); R_{th_{j-s}} = 9K/W$$



Permissible Pulse Handling Capability

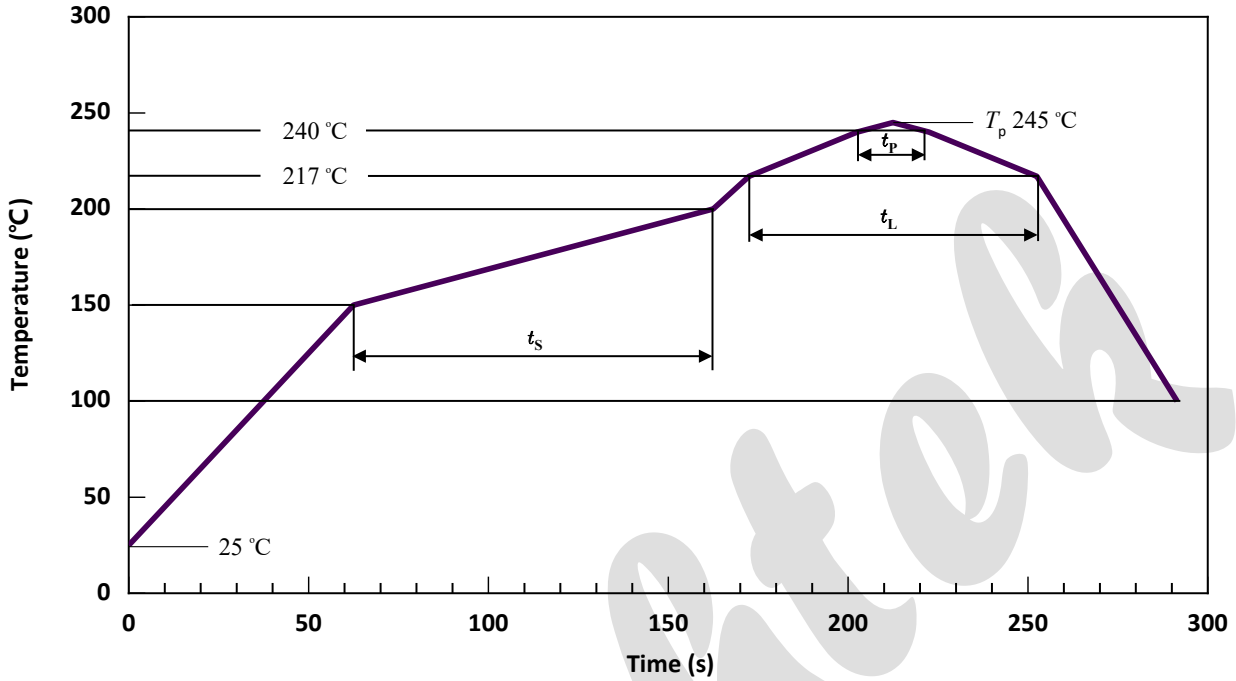
$$I_F = f(t_p); D = \text{Duty cycle}; T_S = 85^\circ\text{C}$$



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Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

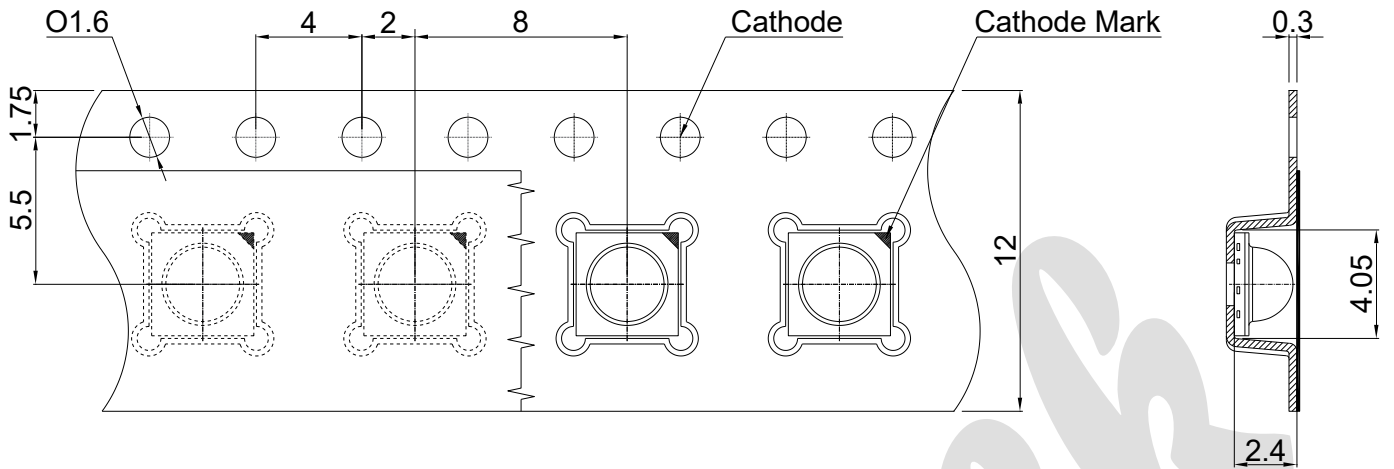


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak T_{Smax} to T_P			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_P		245	260	°C
Time within 5 °C of the specified peak temperature $T_P - 5 K$	T_P	10	20	30	s
Ramp-down Rate T_P to 100 °C			3	4	K/s
Time 25 °C to T_P				480	s

1. Do not stress the silicone resin while it is exposed to high temperature.
2. The reflow process should not exceed 2 times.

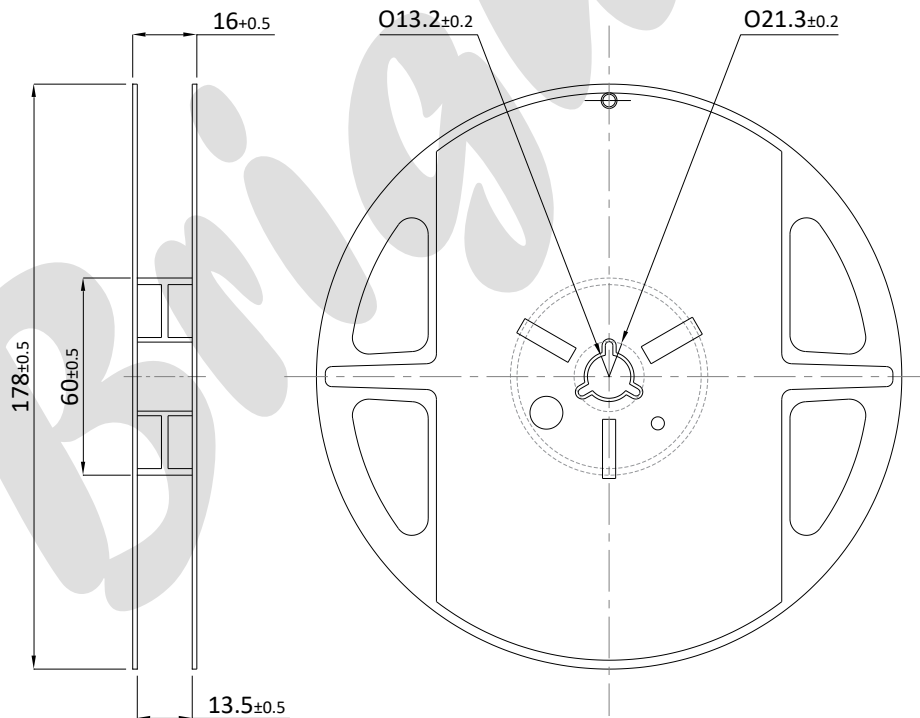
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Dimensions of Tape



1. Dimensions are in millimeters.
2. General tolerance is ± 0.1 mm.


Dimensions of Reel



1. Dimensions are in millimeters.
2. 800 pieces per reel.
3. Dimensions acc. to EIA 481-E

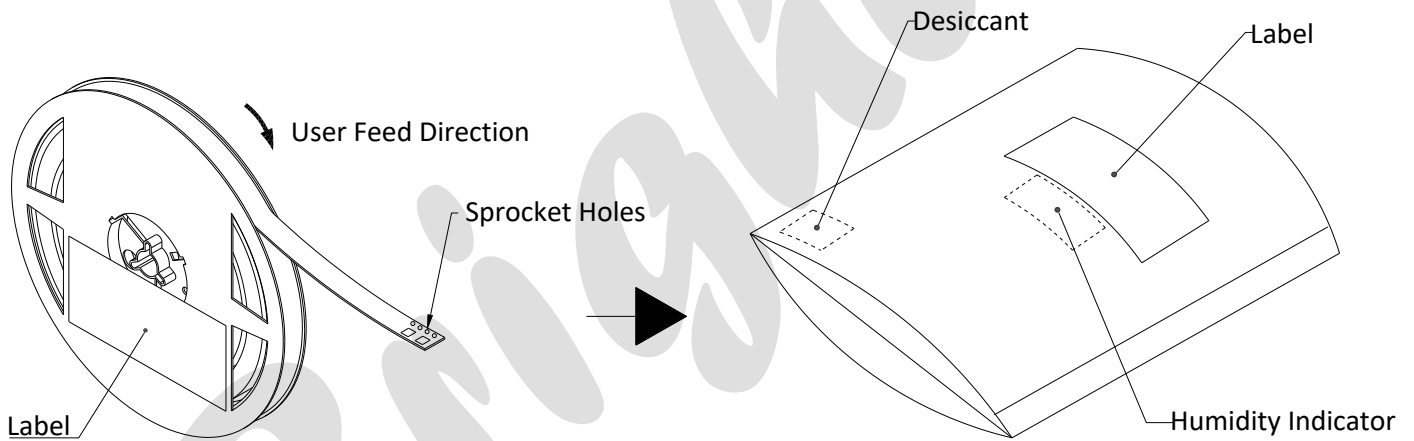
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Barcode-Product-Label (BPL)

		MSL
Part No:		
O Item:		
N Item:		
Q'TY:		
VF:	(mA)	
IV:	(mA)	
WL:	(mA)	
Lot No:		
XXXX-XXXX XXXX / PLSTXXXX	RoHS PASS	

- Part No : Product Number
- O Item : Customer's Product Number
- N Item : Product Name
- Q'TY : Packing Quantity
- VF : Voltage Rank
- IV : Luminous Intensity Rank
- WL : Wavelength Rank
- Lot No : Lot Number
- MSL : MSL Level
- XXXX-XXXX XXXX / PLSTXXXX : Identify Label Number

Dry Packing Process and Materials



1. Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Disclaimer

1. Brightek reserves the right(s) on the adjustment of product material mix for the specification.
2. The product meets Brightek published specification for a period of one year from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Brightek assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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